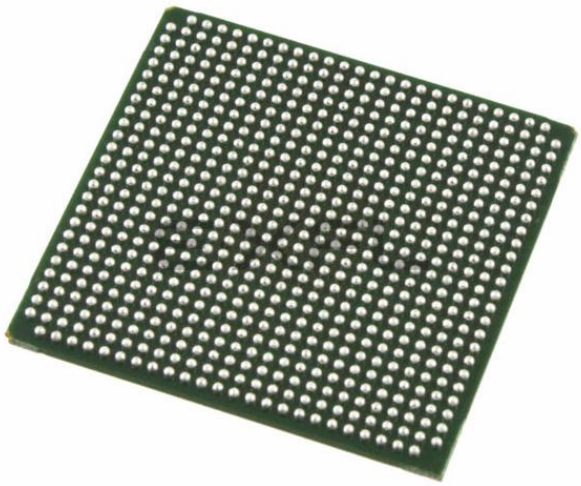
Lattice Semiconductor Corporation - LFE2-35E-6FN672C Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4000
Number of Logic Elements/Cells	32000
Total RAM Bits	339968
Number of I/O	450
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-35e-6fn672c

LatticeECP2/M DSP Performance

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP2/M family.

Table 2-11. DSP Performance

Device	DSP Block	DSP Performance GMAC
ECP2-6	3	3.9
ECP2-12	6	7.8
ECP2-20	7	9.1
ECP2-35	8	10.4
ECP2-50	18	23.4
ECP2-70	22	28.6
ECP2M20	6	7.8
ECP2M35	8	10.4
ECP2M50	22	28.6
ECP2M70	24	31.2
ECP2M100	42	54.6

For further information about the sysDSP block, please see the list of additional technical information at the end of this data sheet.

Programmable I/O Cells (PIC)

Each PIC contains two PIOs connected to their respective sysI/O buffers as shown in Figure 2-28. The PIO Block supplies the output data (DO) and the tri-state control signal (TO) to the sysI/O buffer and receives input from the buffer. Table 2-12 provides the PIO signal list.

Table 2-12. PIO Signals List

Name	Type	Description
CE0, CE1	Control from the core	Clock enables for input and output block flip-flops
CLK0, CLK1	Control from the core	System clocks for input and output blocks
ECLK1, ECLK2	Control from the core	Fast edge clocks
LSR	Control from the core	Local Set/Reset
GSRN	Control from routing	Global Set/Reset (active low)
INCK[2]	Input to the core	Input to Primary Clock Network or PLL reference inputs
DQS	Input to PIO	DQS signal from logic (routing) to PIO
INDD	Input to the core	Unregistered data input to core
INFF	Input to the core	Registered input on positive edge of the clock (CLK0)
IPOS0, IPOS1	Input to the core	Double data rate registered inputs to the core
QPOS0[1], QPOS1[1]	Input to the core	Gearbox pipelined inputs to the core
QNEG0[1], QNEG1[1]	Input to the core	Gearbox pipelined inputs to the core
OPOS0, ONEG0, OPOS2, ONEG2	Output data from the core	Output signals from the core for SDR and DDR operation
OPOS1 ONEG1	Tristate control from the core	Signals to Tristate Register block for DDR operation
DEL[3:0]	Control from the core	Dynamic input delay control bits
TD	Tristate control from the core	Tristate signal from the core used in SDR operation
DDRCLKPOL	Control from clock polarity bus	Controls the polarity of the clock (CLK0) that feed the DDR input block
DQSXFER	Control from core	Controls signal to the Output block

1. Signals available on left/right/bottom only.
2. Selected I/O.

PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

Input Register Block

The input register blocks for PIOs in left, right and bottom edges contain delay elements and registers that can be used to condition high-speed interface signals, such as DDR memory interfaces and source synchronous interfaces, before they are passed to the device core. Figure 2-29 shows the diagram of the input register block for left, right and bottom edges. The input register block for the top edge contains one memory element to register the input signal as shown in Figure 2-30. The following description applies to the input register block for PIOs in the left, right and bottom edges of the device.

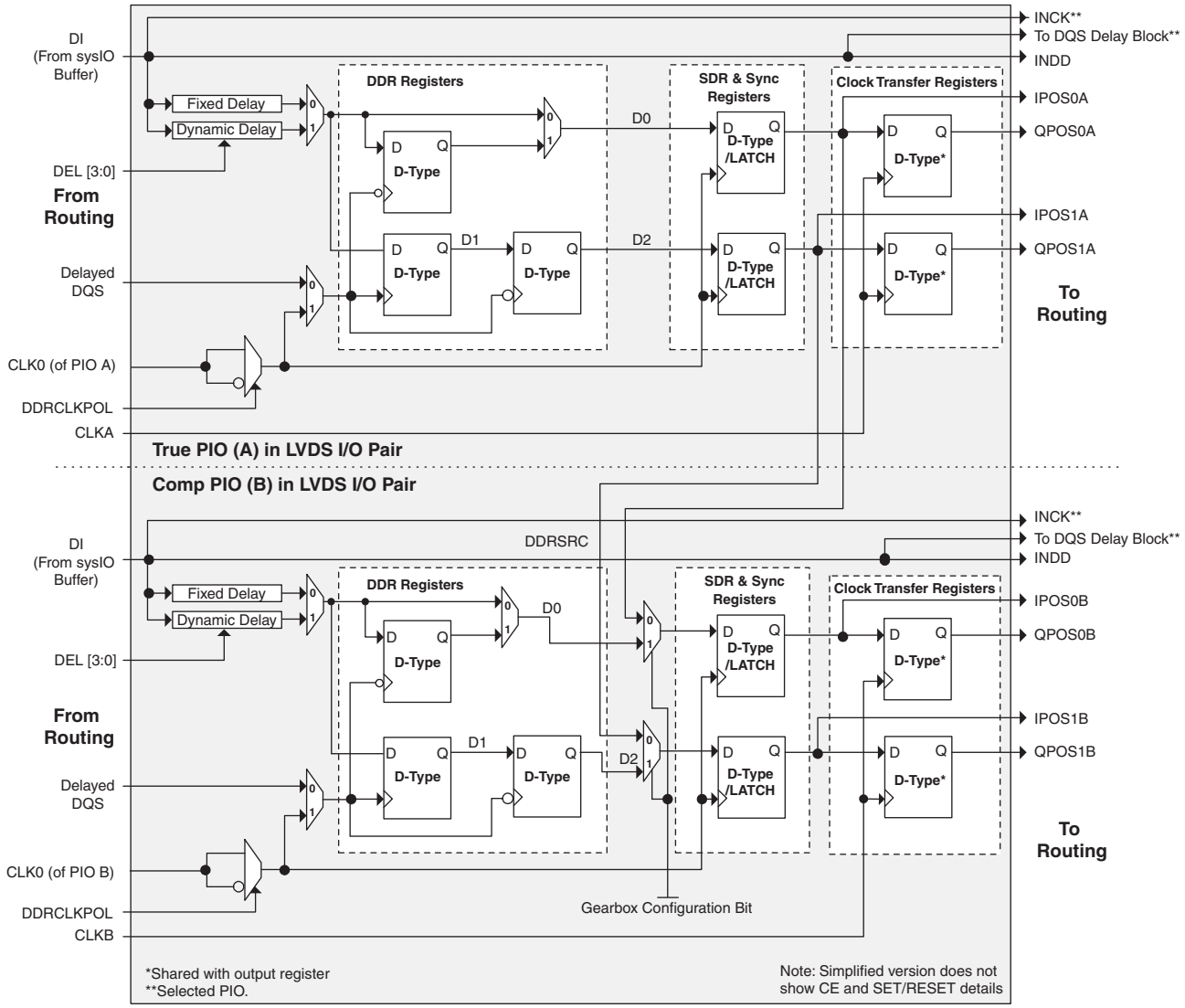
Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired, the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and, in selected blocks, the input to the DQS delay block. If an input delay is desired, designers can select either a fixed delay or a dynamic delay DEL[3:0]. The delay, if selected, reduces input register hold time requirements when using a global clock.

The input block allows three modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In DDR Mode, two registers are used to sample the data on the positive and negative edges of the DQS signal, creating two data streams, D0 and D1. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

By combining input blocks of the complementary PIOs and sharing some registers from output blocks, a gearbox function can be implemented, which takes a double data rate signal applied to PIOA and converts it as four data streams, IPOS0A, IPOS1A, IPOS0B and IPOS1B. Figure 2-29 shows the diagram using this gearbox function. For more information about this topic, please see information regarding additional documentation at the end of this data sheet.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further information about this topic, see the DDR Memory section of this data sheet.

Figure 2-29. Input Register Block for Left, Right and Bottom Edges



SERDES Power Supply Requirements (LatticeECP2M Family Only)[1]

Over Recommended Operating Conditions

Symbol	Description	Typ.[2]	Units
Standby (Power Down)			
$I_{CCTX-SB}$	V_{CCTX} current (per channel)	10	µA
$I_{CCRX-SB}$	V_{CCRX} current (per channel)	75	µA
$I_{CCIB-SB}$	Input buffer current (per channel)	0	µA
$I_{CCOB-SB}$	Output buffer current (per channel)	0	µA
I_{CCP-SB}	SERDES PLL current (per quad)	30	µA
$I_{CCAX33-SB}$	SERDES termination current (per quad)	10	µA
Operating (Data Rate = 3.125 Gbps)			
$I_{CCTX-OP}$	V_{CCTX} current (per channel)	19	mA
$I_{CCRX-OP}$	V_{CCRX} current (per channel)	34	mA
$I_{CCIB-OP}$	Input buffer current (per channel)	4	mA
$I_{CCOB-OP}$	Output buffer current (per channel)	13	mA
I_{CCP-OP}	SERDES PLL current (per quad)	26	mA
$I_{CCAX33-OP}$	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.
2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power[1]

Symbol	Description	Typ.[2]	Units
$P_{S-1CH-31}$	SERDES power (one channel @ 3.125 Gbps)	90	mW
$P_{S-1CH-25}$	SERDES power (one channel @ 2.5 Gbps)	87	mW
$P_{S-1CH-12}$	SERDES power (one channel @ 1.25 Gbps)	86	mW
$P_{S-1CH-02}$	SERDES power (one channel @ 250 Mbps)	76	mW

1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).
2. Typical values measured at 25ºC and 1.2V.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DQVBS}	Data Valid Before DQS (DDR Write)	ECP2/M	0.250	—	0.250	—	0.250	—	UI
t_{DQVAS}	Data Valid After DQS (DDR Write)	ECP2/M	0.250	—	0.250	—	0.250	—	UI
f_{MAX_DDR2}	DDR Clock Frequency	ECP2/M	133	266	133	200	133	166	MHz
SPI4.2 I/O Pin Parameters Static Alignment[4, 8, 11]									
	Maximum Data Rate	ECP2-20	—	750	—	622	—	622	Mbps
		ECP2-35	—	750	—	622	—	622	Mbps
		ECP2-50	—	750	—	622	—	622	Mbps
		ECP2-70	—	750	—	622	—	622	Mbps
		ECP2M20	—	622	—	622	—	622	Mbps
		ECP2M35	—	622	—	622	—	622	Mbps
		ECP2M50	—	622	—	622	—	622	Mbps
		ECP2M70	—	622	—	622	—	622	Mbps
		ECP2M100	—	622	—	622	—	622	Mbps
$t_{DVACLKSPI}$	Data Valid After CLK (Receive)	ECP2-20	—	0.25	—	0.25	—	0.25	UI
		ECP2-35	—	0.25	—	0.25	—	0.25	UI
		ECP2-50	—	0.25	—	0.25	—	0.25	UI
		ECP2-70	—	0.25	—	0.25	—	0.25	UI
		ECP2M20	—	0.21	—	0.21	—	0.21	UI
		ECP2M35	—	0.21	—	0.21	—	0.21	UI
		ECP2M50	—	0.21	—	0.21	—	0.21	UI
		ECP2M70	—	0.21	—	0.21	—	0.21	UI
		ECP2M100	—	0.21	—	0.21	—	0.21	UI
$t_{DVECLKSPI}$	Data Hold After CLK (Receive)	ECP2-20	0.75	—	0.75	—	0.75	—	UI
		ECP2-35	0.75	—	0.75	—	0.75	—	UI
		ECP2-50	0.75	—	0.75	—	0.75	—	UI
		ECP2-70	0.75	—	0.75	—	0.75	—	UI
		ECP2M20	0.79	—	0.79	—	0.79	—	UI
		ECP2M35	0.79	—	0.79	—	0.79	—	UI
		ECP2M50	0.79	—	0.79	—	0.79	—	UI
		ECP2M70	0.79	—	0.79	—	0.79	—	UI
		ECP2M100	0.79	—	0.79	—	0.79	—	UI
t_{DIASPI}	Data Invalid After Clock (Transmit)	ECP2-20	—	280	—	280	—	280	ps
		ECP2-35	—	280	—	280	—	280	ps
		ECP2-50	—	280	—	280	—	280	ps
		ECP2-70	—	280	—	280	—	280	ps
		ECP2M20	—	230	—	230	—	230	ps
		ECP2M35	—	230	—	230	—	230	ps
		ECP2M50	—	230	—	230	—	230	ps
		ECP2M70	—	230	—	230	—	230	ps
		ECP2M100	—	230	—	230	—	230	ps

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DIBSPI}	Data Invalid Before Clock (Transmit)	ECP2-20	—	280	—	280	—	280	ps
		ECP2-35	—	280	—	280	—	280	ps
		ECP2-50	—	280	—	280	—	280	ps
		ECP2-70	—	280	—	280	—	280	ps
		ECP2M20	—	230	—	230	—	230	ps
		ECP2M35	—	230	—	230	—	230	ps
		ECP2M50	—	230	—	230	—	230	ps
		ECP2M70	—	230	—	230	—	230	ps
		ECP2M100	—	230	—	230	—	230	ps
XGMII I/O Pin Parameters (312 Mbps)[5]									
$t_{SUXGMII}$	Data Setup Before Read Clock	ECP2/M	480	—	480	—	480	—	ps
t_{HXGMII}	Data Hold After Read Clock	ECP2/M	480	—	480	—	480	—	ps
$t_{DVBCKXGMII}$	Data Valid Before Clock	ECP2/M	960	—	960	—	960	—	ps
$t_{DVACKXGMII}$	Data Valid After Clock	ECP2/M	960	—	960	—	960	—	ps
Primary									
f_{MAX_PRI}[7]	Frequency for Primary Clock Tree	ECP2/M	—	420	—	357	—	311	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t_{SKEW_PRI}	Primary Clock Skew Within a Bank	ECP2/M	—	300	—	360	—	420	ps
Edge Clock									
f_{MAX_EDGE}[7]	Frequency for Edge Clock	ECP2/M	—	420	—	357	—	311	MHz
t_{W_EDGE}	Clock Pulse Width for Edge Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t_{SKEW_EDGE}	Edge Clock Skew Within an Edge of the Device	ECP2/M	—	300	—	360	—	420	ps

1. General timing numbers based on LVCMOS 2.5, 12mA, 0pf load.
2. DDR timing numbers based on SSTL25 for BGA packages only.
3. DDR2 timing numbers based on SSTL18 for BGA packages only.
4. SPI4.2 and SFI4 timing numbers based on LVDS25 for BGA packages only.
5. XGMII timing numbers based on HSTL class I. A corresponding left/right dedicated clock buffer is used when using the SPI4.2 interface to the left or right edge of the device. For SPI4.2 mode, the software tool will help in selecting the appropriate clock buffer.
6. IP will be used to support DDR and DDR2 memory data rates down to 95MHz. This approach uses a free-running clock and PFU register to sample the data instead of the hardwired DDR memory interface.
7. Using the LVDS I/O standard.
8. ECP2-6 and ECP2-12 do not support SPI4.2
9. The AC numbers do not apply to PCLK6 and PCLK7.
10. Applies to CLKOP only.
11. Please refer to TN1159, LatticeECP2/M Pin Assignment Recommendations for best performance.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

LFE2-12E/SE					LFE2-20E/SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
92	PB44A	4	BDQ42	T	PB54A	4	BDQ51	T
93	VCCIO4	4			VCCIO4	4		
94	PB44B	4	BDQ42	C	PB54B	4	BDQ51	C
95	PB48A	4	BDQ51	T	PB58A	4	BDQ60	T
96	PB48B	4	BDQ51	C	PB58B	4	BDQ60	C
97	VCC	-			VCC	-		
98	PB52A	4	BDQ51	T	PB60A	4	BDQS60	T
99	PB52B	4	BDQ51	C	PB60B	4	BDQ60	C
100	VCCIO4	4			VCCIO4	4		
101	PB54A	4	BDQ51		PB63A	4	BDQ60	
102	GND	-			GND	-		
103	PB55A	4	VREF2_4/BDQ51	T	PB64A	4	VREF2_4/BDQ60	T
104	PB55B	4	VREF1_4/BDQ51	C	PB64B	4	VREF1_4/BDQ60	C
105	CFG1	8			CFG1	8		
106	PROGRAMN	8			PROGRAMN	8		
107	CFG2	8			CFG2	8		
108	INITN	8			INITN	8		
109	CFG0	8			CFG0	8		
110	CCLK	8			CCLK	8		
111	DONE	8			DONE	8		
112	PR29A	8	D0/SPIFASTN		PR43A	8	D0/SPIFASTN	
113	VCCIO8	8			VCCIO8	8		
114	PR26A	8	D6		PR40A	8	D6	
115	GND	-			GND	-		
116	VCC	-			VCC	-		
117	PR25B	8	D7/SPID0	C	PR39B	8	D7/SPID0	C
118	VCCIO8	8			VCCIO8	8		
119	PR25A	8	DI/CSSPI0N	T	PR39A	8	DI/CSSPI0N	T
120	PR24B	8	DOUT/CSON	C	PR38B	8	DOUT/CSON	C
121	PR24A	8	BUSY/SISPI	T	PR38A	8	BUSY/SISPI	T
122	GND	-			GND	-		
123	VCCIO3	3			VCCIO3	3		
124	PR21A	3	RLM0_GPLLT_FB_A		PR31A	3	RLM0_GPLLT_FB_A/RDQ34	
125	VCCAUX	-			VCCAUX	-		
126	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*
127	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*
128	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
129	VCC	-			VCC	-		
130	PR18B	3	RLM0_GDLLC_FB_A	C	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C
131	PR18A	3	RLM0_GDLLT_FB_A	T	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T
132	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*
133	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*
134	PR16B	3	VREF2_3	C	PR22B	3	VREF2_3/RDQ25	C
135	VCCIO3	3			VCCIO3	3		
136	PR16A	3	VREF1_3	T	PR22A	3	VREF1_3/RDQ25	T
137	PR15B	3	PCLKC3_0	C (LVDS)*	PR21B	3	PCLKC3_0/RDQ25	C (LVDS)*

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
A5	A5	PT36B	0		C
A3	A3	PT35B	0		C
A4	A4	PT36A	0		T
VCCIO	VCCIO	VCCIO0	0		
B3	B3	PT35A	0		T
A2	A2	PT34B	0		C
C7	C7	PT33B	0		C
B2	B2	PT34A	0		T
D7	D7	PT33A	0		T
D6	D6	PT32B	0		C
GND	GND	GNDIO0	-		
F7	F7	PT31B	0		C
C6	C6	PT32A	0		T
VCCIO	VCCIO	VCCIO0	0		
F6	F6	PT31A	0		T
C4	C4	PT30B	0		C
B4	B4	PT30A	0		T
-	GND	GNDIO0	0		
-	VCC	VCCIO	0		
D5	D5	PT2B	0	VREF2_0	C
E5	E5	PT2A	0	VREF1_0	T
G7	G7	VCC	-		
G9	G9	VCC	-		
H7	H7	VCC	-		
J10	J10	VCC	-		
K10	K10	VCC	-		
K8	K8	VCC	-		
G8	G8	VCCAUX	-		
H10	H10	VCCAUX	-		
J7	J7	VCCAUX	-		
K9	K9	VCCAUX	-		
C5	C5	VCCIO0	0		
E7	E7	VCCIO0	0		
C12	C12	VCCIO1	1		
E10	E10	VCCIO1	1		
E14	E14	VCCIO2	2		
G12	G12	VCCIO2	2		
K12	K12	VCCIO3	3		
M14	M14	VCCIO3	3		
M10	M10	VCCIO4	4		
P12	P12	VCCIO4	4		
M7	M7	VCCIO5	5		

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K8	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L12	GND	-			GND	-		
L13	GND	-			GND	-		
L15	GND	-			GND	-		
L8	GND	-			GND	-		
M10	GND	-			GND	-		
M11	GND	-			GND	-		
M12	GND	-			GND	-		
M13	GND	-			GND	-		
M15	GND	-			GND	-		
M8	GND	-			GND	-		
N10	GND	-			GND	-		
N11	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N15	GND	-			GND	-		
N8	GND	-			GND	-		
P14	GND	-			GND	-		
P20	GND	-			GND	-		
P3	GND	-			GND	-		
P9	GND	-			GND	-		
R10	GND	-			GND	-		
R11	GND	-			GND	-		
R12	GND	-			GND	-		
R13	GND	-			GND	-		
U17	GND	-			GND	-		
U6	GND	-			GND	-		
W2	GND	-			GND	-		
W21	GND	-			GND	-		
Y14	GND	-			GND	-		
Y9	GND	-			GND	-		
A1	GND	-			GND	-		
N18	VCCPLL	-			VCCPLL	-		
K6	NC	-			VCCPLL	-		
N6	VCCPLL	-			VCCPLL	-		
J16	NC	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D2	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7/LDQ6	T (LVDS)*
D1	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7/LDQ6	C (LVDS)*
GND	GNDIO7	-			GNDIO7	-		
F6	PL3A	7		T	PL3A	7	LDQ6	T
F5	PL3B	7		C	PL3B	7	LDQ6	C
VCCIO	VCCIO7	7			VCCIO7	7		
E4	NC	-			PL4A	7	LDQ6	T (LVDS)*
E3	NC	-			PL4B	7	LDQ6	C (LVDS)*
E2	NC	-			PL5A	7	LDQ6	T
E1	NC	-			PL5B	7	LDQ6	C
GND	GNDIO7	-			GNDIO7	-		
H6	NC	-			PL6A	7	LDQS6	T (LVDS)*
H5	NC	-			PL6B	7	LDQ6	C (LVDS)*
F2	NC	-			PL7A	7	LDQ6	T
VCCIO	VCCIO7	7			VCCIO7	7		
F1	NC	-			PL7B	7	LDQ6	C
H8	NC	-			PL8A	7	LDQ6	T (LVDS)*
J9	NC	-			PL8B	7	LDQ6	C (LVDS)*
G4	NC	-			PL9A	7	LDQ6	T
GND	GNDIO7	-			GNDIO7	-		
G3	NC	-			PL9B	7	LDQ6	C
H7	PL4A	7	LDQ8	T (LVDS)*	PL10A	7	LDQ14	T (LVDS)*
J8	PL4B	7	LDQ8	C (LVDS)*	PL10B	7	LDQ14	C (LVDS)*
G2	PL5A	7	LDQ8	T	PL11A	7	LDQ14	T
G1	PL5B	7	LDQ8	C	PL11B	7	LDQ14	C
H3	PL6A	7	LDQ8	T (LVDS)*	PL12A	7	LDQ14	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO7	7		
H4	PL6B	7	LDQ8	C (LVDS)*	PL12B	7	LDQ14	C (LVDS)*
J5	PL7A	7	LDQ8	T	PL13A	7	LDQ14	T
J4	PL7B	7	LDQ8	C	PL13B	7	LDQ14	C
J3	PL8A	7	LDQS8	T (LVDS)*	PL14A	7	LDQS14	T (LVDS)*
GND	GNDIO7	-			GNDIO7	-		
K4	PL8B	7	LDQ8	C (LVDS)*	PL14B	7	LDQ14	C (LVDS)*
H1	PL9A	7	LDQ8	T	PL15A	7	LDQ14	T
H2	PL9B	7	LDQ8	C	PL15B	7	LDQ14	C
VCCIO	VCCIO7	7			VCCIO7	7		
K6	PL10A	7	LDQ8	T (LVDS)*	PL16A	7	LDQ14	T (LVDS)*
K7	PL10B	7	LDQ8	C (LVDS)*	PL16B	7	LDQ14	C (LVDS)*
J1	PL11A	7	LDQ8	T	PL17A	7	LDQ14	T
J2	PL11B	7	LDQ8	C	PL17B	7	LDQ14	C
GND	GNDIO7	-			GNDIO7	-		
VCCIO	VCCIO7	7			VCCIO7	7		
K3	NC	-			NC	-		
K2	NC	-			NC	-		
GND	GNDIO7	-			GNDIO7	-		
K1	NC	-			NC	-		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W5	PL71B	6	LDQ75	C (LVDS)*	PL84B	6	LDQ88	C (LVDS)*
AC1	PL72A	6	LDQ75	T	PL85A	6	LDQ88	T
AD1	PL72B	6	LDQ75	C	PL85B	6	LDQ88	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y6	PL73A	6	LDQ75	T (LVDS)*	PL86A	6	LDQ88	T (LVDS)*
Y5	PL73B	6	LDQ75	C (LVDS)*	PL86B	6	LDQ88	C (LVDS)*
AE2	PL74A	6	LDQ75	T	PL87A	6	LDQ88	T
AD2	PL74B	6	LDQ75	C	PL87B	6	LDQ88	C
GND	GNDIO6	-			GNDIO6	-		
AB3	PL75A	6	LDQS75	T (LVDS)*	PL88A	6	LDQS88	T (LVDS)*
AB2	PL75B	6	LDQ75	C (LVDS)*	PL88B	6	LDQ88	C (LVDS)*
W7	PL76A	6	LDQ75	T	PL89A	6	LDQ88	T
VCCIO	VCCIO6	6			VCCIO6	6		
W8	PL76B	6	LDQ75	C	PL89B	6	LDQ88	C
Y7	PL77A	6	LDQ75	T (LVDS)*	PL90A	6	LDQ88	T (LVDS)*
Y8	PL77B	6	LDQ75	C (LVDS)*	PL90B	6	LDQ88	C (LVDS)*
AC2	PL78A	6	LDQ75	T	PL91A	6	LDQ88	T
GND	GNDIO6	-			GNDIO6	-		
AD3	PL78B	6	LDQ75	C	PL91B	6	LDQ88	C
AC3	TCK	-			TCK	-		
AA8	TDI	-			TDI	-		
AB4	TMS	-			TMS	-		
AA5	TDO	-			TDO	-		
AB5	VCCJ	-			VCCJ	-		
AE3	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
AF3	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
AC4	PB3A	5	BDQ6	T	PB3A	5	BDQ6	T
AD4	PB3B	5	BDQ6	C	PB3B	5	BDQ6	C
AE4	PB4A	5	BDQ6	T	PB4A	5	BDQ6	T
AF4	PB4B	5	BDQ6	C	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
V9	PB5A	5	BDQ6	T	PB5A	5	BDQ6	T
W9	PB5B	5	BDQ6	C	PB5B	5	BDQ6	C
GND	GNDIO5	-			GNDIO5	-		
AA6	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
AB6	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
AC5	PB7A	5	BDQ6	T	PB7A	5	BDQ6	T
AD5	PB7B	5	BDQ6	C	PB7B	5	BDQ6	C
AA7	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
AB7	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
AE5	PB9A	5	BDQ6	T	PB9A	5	BDQ6	T
AF5	PB9B	5	BDQ6	C	PB9B	5	BDQ6	C
AC7	PB10A	5	BDQ6	T	PB10A	5	BDQ6	T
AD7	PB10B	5	BDQ6	C	PB10B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO5	-			GNDIO5	-		
W10	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
Y10	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
W11	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AA10	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AC8	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
AD8	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
AB8	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
AB10	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
GND	GNDIO5	-			GNDIO5	-		
AE6	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
AF6	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AA11	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
AC9	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
AB9	PB26A	5	BDQ24	T	PB35A	5	BDQ33	T
AD9	PB26B	5	BDQ24	C	PB35B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y11	PB27A	5	BDQ24	T	PB36A	5	BDQ33	T
AB11	PB27B	5	BDQ24	C	PB36B	5	BDQ33	C
AE7	PB28A	5	BDQ24	T	PB37A	5	BDQ33	T
AF7	PB28B	5	BDQ24	C	PB37B	5	BDQ33	C
GND	GNDIO5	-			GNDIO5	-		
AC10	PB29A	5	BDQ33	T	PB38A	5	BDQ42	T
AD10	PB29B	5	BDQ33	C	PB38B	5	BDQ42	C
AA12	PB30A	5	BDQ33	T	PB39A	5	BDQ42	T
W12	PB30B	5	BDQ33	C	PB39B	5	BDQ42	C
AB12	PB31A	5	BDQ33	T	PB40A	5	BDQ42	T
VCCIO	VCCIO5	5			VCCIO5	5		
Y12	PB31B	5	BDQ33	C	PB40B	5	BDQ42	C
AD12	PB32A	5	BDQ33	T	PB41A	5	BDQ42	T
AC12	PB32B	5	BDQ33	C	PB41B	5	BDQ42	C
AC13	PB33A	5	BDQS33	T	PB42A	5	BDQS42	T
GND	GNDIO5	-			GNDIO5	-		
AA13	PB33B	5	BDQ33	C	PB42B	5	BDQ42	C
AD13	PB34A	5	BDQ33	T	PB43A	5	BDQ42	T
AC14	PB34B	5	BDQ33	C	PB43B	5	BDQ42	C
AE8	PB35A	5	BDQ33	T	PB44A	5	BDQ42	T
VCCIO	VCCIO5	5			VCCIO5	5		
AF8	PB35B	5	BDQ33	C	PB44B	5	BDQ42	C
AB15	PB36A	5	BDQ33	T	PB45A	5	BDQ42	T
Y13	PB36B	5	BDQ33	C	PB45B	5	BDQ42	C
AE9	PB37A	5	BDQ33	T	PB46A	5	BDQ42	T
GND	GNDIO5	-			GNDIO5	-		
AF9	PB37B	5	BDQ33	C	PB46B	5	BDQ42	C
W13	PB38A	5	BDQ42	T	PB47A	5	BDQ51	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A7	PT35B	0		C	PT44B	0		C
B7	PT35A	0		T	PT44A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F12	PT34B	0		C	PT43B	0		C
D10	PT34A	0		T	PT43A	0		T
H11	PT33B	0		C	PT42B	0		C
G11	PT33A	0		T	PT42A	0		T
GND	GNDIO0	-			GNDIO0	-		
A6	PT32B	0		C	PT41B	0		C
B6	PT32A	0		T	PT41A	0		T
D8	PT31B	0		C	PT40B	0		C
C8	PT31A	0		T	PT40A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F11	PT30B	0		C	PT39B	0		C
E10	PT30A	0		T	PT39A	0		T
E9	PT29B	0		C	PT38B	0		C
D9	PT29A	0		T	PT38A	0		T
G10	PT28B	0		C	PT37B	0		C
GND	GNDIO0	-			GNDIO0	-		
H10	PT28A	0		T	PT37A	0		T
A5	PT27B	0		C	PT36B	0		C
B5	PT27A	0		T	PT36A	0		T
C7	PT26B	0		C	PT35B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
D7	PT26A	0		T	PT35A	0		T
E8	PT25B	0		C	PT34B	0		C
F10	PT25A	0		T	PT34A	0		T
F8	PT24B	0		C	PT33B	0		C
H9	PT24A	0		T	PT33A	0		T
C5	PT23B	0		C	PT32B	0		C
GND	GNDIO0	-			GNDIO0	-		
D5	PT23A	0		T	PT32A	0		T
B4	PT22B	0			PT31B	0		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
C4	PT10B	0		C	PT10B	0		C
GND	GNDIO0	-			GNDIO0	-		
C3	PT10A	0		T	PT10A	0		T
A4	PT9B	0		C	PT9B	0		C
A3	PT9A	0		T	PT9A	0		T
B3	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
B2	PT8A	0		T	PT8A	0		T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AB24	PR87B	8	D3	C
GND	GNDIO4	-		
AB23	PR87A	8	D4	T
AB25	PR86B	8	D5	C
AB26	PR86A	8	D6	T
AC27	PR85B	8	D7/SPID0	C
VCCIO	VCCIO8	8		
AB27	PR85A	8	DI/CSSPI0N	T
AD29	PR84B	8	DOUT/CSON	C
AD30	PR84A	8	BUSY/SISPI	T
AA25	PR83B	3	RDQ80	C
GND	GNDIO3	-		
AA23	PR83A	3	RDQ80	T
AC29	PR82B	3	RDQ80	C (LVDS)*
AC30	PR82A	3	RDQ80	T (LVDS)*
AA26	PR81B	3	RDQ80	C
VCCIO	VCCIO3	3		
AA24	PR81A	3	RDQ80	T
AB29	PR80B	3	RDQ80	C (LVDS)*
AB30	PR80A	3	RDQS80	T (LVDS)*
GND	GNDIO3	-		
Y23	PR79B	3	RDQ80	C
Y25	PR79A	3	RDQ80	T
AA27	PR78B	3	RDQ80	C (LVDS)*
AA28	PR78A	3	RDQ80	T (LVDS)*
VCCIO	VCCIO3	3		
Y24	PR77B	3	RLM0_GPLLC_FB_A/RDQ80	C
Y26	PR77A	3	RLM0_GPLLT_FB_A/RDQ80	T
AA29	PR76B	3	RLM0_GPLLC_IN_A**/RDQ80	C (LVDS)*
AA30	PR76A	3	RLM0_GPLLT_IN_A**/RDQ80	T (LVDS)*
R22	RLM0_PLLCAP	3		
W23	PR74B	3	RLM0_GDLLC_FB_A/RDQ71	C
W25	PR74A	3	RLM0_GDLLT_FB_A/RDQ71	T
GND	GNDIO3	-		
Y27	PR73B	3	RLM0_GDLLC_IN_A**/RDQ71	C (LVDS)*
Y28	PR73A	3	RLM0_GDLLT_IN_A**/RDQ71	T (LVDS)*
W24	PR72B	3	RDQ71	C
W26	PR72A	3	RDQ71	T
VCCIO	VCCIO3	3		
Y29	PR71B	3	RDQ71	C (LVDS)*
Y30	PR71A	3	RDQS71	T (LVDS)*
V25	PR70B	3	RDQ71	C
GND	GNDIO3	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W18	GND	-		
W19	GND	-		
Y14	GND	-		
Y15	GND	-		
Y16	GND	-		
Y17	GND	-		
A2	NC	-		
A3	NC	-		
A4	NC	-		
A5	NC	-		
AB28	NC	-		
AC4	NC	-		
AD23	NC	-		
AE1	NC	-		
AE2	NC	-		
AE29	NC	-		
AE3	NC	-		
AE30	NC	-		
AE4	NC	-		
AE5	NC	-		
AE6	NC	-		
AF1	NC	-		
AF2	NC	-		
AF23	NC	-		
AF26	NC	-		
AF27	NC	-		
AF28	NC	-		
AF29	NC	-		
AF3	NC	-		
AF30	NC	-		
AF4	NC	-		
AF5	NC	-		
AG1	NC	-		
AG13	NC	-		
AG16	NC	-		
AG18	NC	-		
AG2	NC	-		
AG26	NC	-		
AG27	NC	-		
AG28	NC	-		
AG29	NC	-		
AG3	NC	-		
AG30	NC	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
E27	NC	-		
E28	NC	-		
E29	NC	-		
E3	NC	-		
E30	NC	-		
E4	NC	-		
E5	NC	-		
E6	NC	-		
F25	NC	-		
F5	NC	-		
F6	NC	-		
G6	NC	-		
G7	NC	-		
K10	NC	-		
K9	NC	-		
N27	NC	-		
N4	NC	-		
R1	NC	-		
R2	NC	-		
V27	NC	-		
V4	NC	-		
P22	VCCPLL	-		
P8	VCCPLL	-		
T22	VCCPLL	-		
Y7	VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
A9	ULC_SQ_HDOUTP0	11		T
A10	ULC_SQ_VCCOB0	11		
B9	ULC_SQ_HDOUTN0	11		C
C9	ULC_SQ_VCCTX1	11		
B8	ULC_SQ_HDOUTN1	11		C
C8	ULC_SQ_VCCOB1	11		
A8	ULC_SQ_HDOUTP1	11		T
C12	ULC_SQ_VCCRX1	11		
B11	ULC_SQ_HDINN1	11		C
C11	ULC_SQ_VCCIB1	11		
A11	ULC_SQ_HDINP1	11		T
B7	ULC_SQ_VCCAUX33	11		
E7	ULC_SQ_REFCLKN	11		C
D7	ULC_SQ_REFCLKP	11		T
C7	ULC_SQ_VCCP	11		
A3	ULC_SQ_HDINP2	11		T
C3	ULC_SQ_VCCIB2	11		
B3	ULC_SQ_HDINN2	11		C
C2	ULC_SQ_VCCRX2	11		
A6	ULC_SQ_HDOUTP2	11		T
C6	ULC_SQ_VCCOB2	11		
B6	ULC_SQ_HDOUTN2	11		C
C5	ULC_SQ_VCCTX2	11		
B5	ULC_SQ_HDOUTN3	11		C
A4	ULC_SQ_VCCOB3	11		
A5	ULC_SQ_HDOUTP3	11		T
C4	ULC_SQ_VCCTX3	11		
B2	ULC_SQ_HDINN3	11		C
B1	ULC_SQ_VCCIB3	11		
A2	ULC_SQ_HDINP3	11		T
C1	ULC_SQ_VCCRX3	11		
L12	VCC	-		
L13	VCC	-		
L18	VCC	-		
L19	VCC	-		
M11	VCC	-		
M12	VCC	-		
M13	VCC	-		
M14	VCC	-		
M15	VCC	-		
M16	VCC	-		
M17	VCC	-		
M18	VCC	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AE27	GND	-		
AE4	GND	-		
AE9	GND	-		
AF14	GND	-		
AF17	GND	-		
AF25	GND	-		
AF6	GND	-		
AJ10	GND	-		
AJ21	GND	-		
AJ27	GND	-		
AJ4	GND	-		
AK1	GND	-		
AK13	GND	-		
AK18	GND	-		
AK24	GND	-		
AK30	GND	-		
AK7	GND	-		
B10	GND	-		
B21	GND	-		
B27	GND	-		
B4	GND	-		
D25	GND	-		
D6	GND	-		
E14	GND	-		
E17	GND	-		
F22	GND	-		
F27	GND	-		
F4	GND	-		
F9	GND	-		
G12	GND	-		
G19	GND	-		
J24	GND	-		
J7	GND	-		
K14	GND	-		
K15	GND	-		
K16	GND	-		
K17	GND	-		
K27	GND	-		
K4	GND	-		
L14	GND	-		
L15	GND	-		
L16	GND	-		
L17	GND	-		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5F1152C	436	1.2V	-5	fpBGA	1152	Com	70
LFE2M70SE-6F1152C	436	1.2V	-6	fpBGA	1152	Com	70
LFE2M70SE-7F1152C	436	1.2V	-7	fpBGA	1152	Com	70
LFE2M70SE-5F900C	416	1.2V	-5	fpBGA	900	Com	70
LFE2M70SE-6F900C	416	1.2V	-6	fpBGA	900	Com	70
LFE2M70SE-7F900C	416	1.2V	-7	fpBGA	900	Com	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5F1152C	520	1.2V	-5	fpBGA	1152	Com	100
LFE2M100SE-6F1152C	520	1.2V	-6	fpBGA	1152	Com	100
LFE2M100SE-7F1152C	520	1.2V	-7	fpBGA	1152	Com	100
LFE2M100SE-5F900C	416	1.2V	-5	fpBGA	900	Com	100
LFE2M100SE-6F900C	416	1.2V	-6	fpBGA	900	Com	100
LFE2M100SE-7F900C	416	1.2V	-7	fpBGA	900	Com	100

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.